

01-07-2005



MRD  
1/3/05  
**IN THE UNITED**

**102915837**

**MARK OFFICE**

Applicant: Charles W.C. Lin et al.  
Assignee: Bridge Semiconductor Corporation  
Title: THREE-DIMENSIONAL STACKED SEMICONDUCTOR PACKAGE WITH METAL PILLAR IN ENCAPSULANT APERTURE  
Serial No.: 10/966,816 Filed: October 15, 2004  
Examiner: Unknown Group Art Unit: 2818  
Atty. Docket No.: BDG026

FINANCE SECTION

2005 JAN -3 PM 2:45

OFFICE OF THE COMPTROLLER

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Alexandria, VA 22313-1450

**ASSIGNMENT RECORDATION COVER SHEET**

Dear Sir:

Please record the attached original Assignment.

1. Name of conveying party:

Cheng-Lien Chiang

2. Name and address of receiving party:

Bridge Semiconductor Corporation  
3<sup>rd</sup> Floor, 157 Li-Te Road  
Peitou District  
Taipei, Taiwan 112

3. Nature of conveyance:

Assignment

The execution date of the Assignment is November 9, 2004.

-1-

Serial No. 10/966,816

01/06/2005 MESTACHE 00000142 502170 10966816

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**PATENT**  
**REEL: 016123 FRAME: 0681**

4. Application number(s) or patent number(s)

This Assignment is being filed for U.S. Application Serial No. 10/966,816 filed October 15, 2004.

5. Name and address of party to whom correspondence should be mailed:

David M. Sigmond  
487 Blackfoot Street  
Superior, Colorado 80027

(303) 554-8371

6. Total number of applications and patents involved: 1.

7. Total fee under 37 C.F.R. § 1.21(h): \$40.

8. Method of Payment:

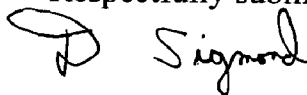
Charge the \$40 to Deposit Account No. 502178/BDG026 and charge any underpayment or credit any overpayment to this Account.

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Total number of pages including cover sheet, attachments and document: 3.

Respectfully submitted,



David M. Sigmond  
Attorney for Applicant  
Reg. No. 34,013  
(303) 554-8371  
(303) 554-8667 (fax)

Date: Dec 29, 2004

## ASSIGNMENT

WHEREAS, we, CHARLES W.C. LIN of Singapore, and CHENG-LIEN CHIANG of Taipei, Taiwan, have invented a certain new and useful invention entitled THREE-DIMENSIONAL STACKED SEMICONDUCTOR PACKAGE WITH METAL PILLAR IN ENCAPSULANT APERTURE, for which an application for Letters Patent of the United States has been prepared for filing, said application being identified as Serial No. 10/966,816 filed on October 15, 2004;

NOW THEREFORE, be it known that we, the said inventors, for and in consideration of certain good and valuable consideration, the sufficiency and receipt of which is hereby acknowledged, at the request of the assignee do sell, assign and transfer unto said assignee, BRIDGE SEMICONDUCTOR CORPORATION, a Taiwan Corporation having a place of business at 3<sup>rd</sup> Floor, 157 Li-Te Road, Peitou District, Taipei, Taiwan 112, its successors, legal representatives and assigns, the aforesaid application for the territory of the United States of America and all continuation, divisional, continuation-in-part and reissue applications, all patent applications in foreign countries, all applications pursuant to the Patent Cooperation Treaty, and all applications for extension filed or to be filed for the invention, and all Letters Patent, Invention Registrations, Utility Models, Extensions or Reissues, Reexaminations and other patent rights, obtained for the invention in the United States or any other country; we also assign any right, title or interest in and to the invention which has not already been transferred to the assignee; we warrant that we have made no assignment of the invention, application or patent therefor to a party other than BRIDGE SEMICONDUCTOR CORPORATION and we are under no obligation to make and shall not make any assignment of the invention, application, or patent therefor to any other party; and we further agree to cooperate with the assignee hereunder in obtaining, sustaining and enforcing of any and all such Letters Patent and patent rights and in confirming the assignee's exclusive ownership of the invention, without further consideration, but at the expense of said assignee.

The Commissioner of Patents is hereby authorized and requested to issue the Letters Patent solely in accordance with the terms of this Assignment to BRIDGE SEMICONDUCTOR CORPORATION, its successors, legal representatives and assigns, as the assignee of the entire right, title and interest therein.

IN WITNESS WHEREOF, the parties hereto have executed this Assignment as of the date indicated hereunder.

Date: \_\_\_\_\_

By: \_\_\_\_\_

CHARLES W.C. LIN

Date: 11/9 2004

By: Cheng-lien Chiang 11/9 2004

CHENG-LIEN CHIANG